

Title (en)  
TITANIUM-BASE CERMET, COATED CERMET, AND CUTTING TOOL

Title (de)  
CERMET AUF TITANBASIS, BESCHICHTETER CERMET UND SCHNEIDWERKZEUG

Title (fr)  
CERMET À BASE DE TITANE, CERMET ENROBÉ ET OUTIL TRANCHANT

Publication  
**EP 2177639 B1 20200304 (EN)**

Application  
**EP 08791644 A 20080725**

Priority  

- JP 2008063400 W 20080725
- JP 2007195909 A 20070727
- JP 2007195910 A 20070727
- JP 2007306887 A 20071128

Abstract (en)  
[origin: EP2177639A1] There is provided a Ti-based cermet suitable for a cutting tool having high fracture resistance and wear resistance. The Ti-based cermet 1 is composed of at least one kind of element selected from Co and Ni, and one or more kinds of substances selected from carbides, nitrides, and carbonitrides of one or more kinds of metals selected from Group 4, Group 5, and Group 6 metals of the periodic table, each of which is composed mainly of Ti, and 0.1 to 0.5% by mass of Mn. In a scanning electron microscope (SEM) photograph of an arbitrary cross-section of the Ti-based cermet, a surface region is formed in which a hard phase 2 whose interior comprises a first hard phase 2a and a second hard phase 2b, and a binder phase 3 composed mainly of at least one kind of element selected from Co and Ni are observed, and the second hard phase 2b looks whiter than the first hard phase 2a, and the second hard phase 2b whose content percentage is not less than 90% by area is observed in a surface part.

IPC 8 full level  
**C22C 29/04** (2006.01); **B22F 7/06** (2006.01); **B23B 27/14** (2006.01); **C22C 1/05** (2006.01)

CPC (source: EP)  
**B22F 7/06** (2013.01); **C22C 1/051** (2013.01); **C22C 29/04** (2013.01); **B22F 2005/001** (2013.01); **B22F 2999/00** (2013.01); **C22C 2204/00** (2013.01)

Cited by  
EP2752263A4; EP2687310A4; US8808871B2

Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)  
**EP 2177639 A1 20100421**; **EP 2177639 A4 20120321**; **EP 2177639 B1 20200304**; CN 101790594 A 20100728; CN 101790594 B 20130619; JP 5328653 B2 20131030; JP WO2009017053 A1 20101021; WO 2009017053 A1 20090205

DOCDB simple family (application)  
**EP 08791644 A 20080725**; CN 200880100278 A 20080725; JP 2008063400 W 20080725; JP 2009525370 A 20080725